

2709516

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DIN rail housing, Lower housing part with metal foot catch, tall design, with vents, width: 17.6 mm, height: 99 mm, depth: 107.3 mm, color: green (similar RAL 6021), cross connection: DIN rail connector (optional), number of positions cross connector: 5

### Your advantages

- Tool-free mounting
- · Available in overall widths from 12.5 mm to 90 mm, modular extension possible
- · Flammability rating V0 in accordance with UL 94
- · Variety of connection technology
- · Can be mounted on the DIN rail
- With integrated or DIN-rail-mountable bus connector as an option

### Commercial data

Item number	2709516
Packing unit	10 pc
Minimum order quantity	10 рс
Sales key	AC08
Product key	ACHAAC
Catalog page	Page 325 (CC-2002)
GTIN	4017918902193
Weight per piece (including packing)	39.94 g
Weight per piece (excluding packing)	33.738 g
Customs tariff number	85389099
Country of origin	DE

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## Technical data

### Notes

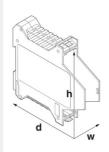
General	Refer to the data sheet for the range in the download area.
General	Material of contact pads for bus connector, galvanic gold (hard gold)

### Product properties

Туре	Lower housing parts with vents, housing cover necessary to complete the module
Product type	Enclosure bottom part
Housing series	ME
Product family	ME UT TBUS
Туре	Lower housing part with metal foot catch, tall design
Housing type	DIN rail housing
Ventilation openings present	yes

### Dimensions

Dimensional drawing



Width	17.6 mm
Height	99 mm
Depth	107.3 mm
Depth from top edge of DIN rail	100.7 mm
Depth from top edge of DIN rail to support point on upper part	68.5 mm

#### PCB design

#### Material specifications

Color (Housing)	green (RAL 6021)
Flammability rating according to UL 94	VO
CTI according to IEC 60112	600
Surface characteristics	untreated
Housing material	Polyamide

### Environmental and real-life conditions

Power dissipation single housing for 20  $^\circ\text{C}$ 

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Temperature	850 °C
Specification	IEC 60695-2-11:2014-02
Glow-wire test	
Test directions	X-, Y- and Z-axis
Test duration per axis	2.5 h
Acceleration	2g (58.1 Hz 150 Hz)
Amplitude	0.15 mm (10 Hz 58.1 Hz)
Sweep speed	1 octave/min
Frequency	10 - 150 - 10 Hz
Specification	IEC 60068-2-6:2007-12
Vibration test	
Power dissipation	2.5 W
Mounting position	vertical
Reduction factor	0.49
Ambient temperature	70 °C
Power dissipation single housing for 70 °C	
Power dissipation	3 W
Mounting position	vertical
Reduction factor	0.57
Ambient temperature	60 °C
Power dissipation single housing for 60 °C	
Power dissipation	3.6 W
Mounting position	vertical
Reduction factor	0.7
Ambient temperature	50 °C
Power dissipation single housing for 50 °C	50.00
Power dissipation	4.2 W
Mounting position	vertical
Reduction factor	0.81
Ambient temperature	40 °C
Power dissipation single housing for 40 °C	
Power dissipation	4.7 W
Mounting position	vertical
Reduction factor	0.91
Ambient temperature	30 °C
Power dissipation single housing for 30 °C	
Power dissipation	5.2 W
Mounting position	vertical
Reduction factor	
Doduction footor	1



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	30 s
Time of exposure	
hermal stability / ball thrust test	
Specification	IEC 60695-10-2:2014-02
Temperature	125 °C
Test duration	1 h
Force	20 N
lechanical strength / tumbling barrel	
Specification	IEC 60998-1:2002-12
Height of fall	50 cm
Frequency	10
hocks	
Specification	IEC 60068-2-27:2008-02
Pulse shape	Half-sine
Acceleration	15g
Shock duration	11 ms
Number of shocks per direction	3
Test directions egree of protection (IP code) Specification	X-, Y- and Z-axis (pos. and neg.) IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0
egree of protection (IP code) Specification	
egree of protection (IP code) Specification mbient conditions	
egree of protection (IP code) Specification mbient conditions Max. IP code to attain	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-08
egree of protection (IP code) Specification mbient conditions Max. IP code to attain Ambient temperature (operation)	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-0
egree of protection (IP code) Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport)	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-08 IP20 -40 °C 105 °C (depending on power dissipation)
egree of protection (IP code) Specification mbient conditions Max. IP code to attain Ambient temperature (operation)	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-04 IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 55 °C
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egree of protection (IP code) Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport)	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-08   IP20   -40 °C 105 °C (depending on power dissipation)   -40 °C 55 °C   -5 °C 100 °C
egree of protection (IP code) Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-08 IP20 -40 °C 105 °C (depending on power dissipation) -40 °C 55 °C -5 °C 100 °C 80 %
egree of protection (IP code) Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-04   IP20   -40 °C 105 °C (depending on power dissipation)   -40 °C 55 °C   -5 °C 100 °C   80 %
egree of protection (IP code) Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-08   IP20   -40 °C 105 °C (depending on power dissipation)   -40 °C 55 °C   -5 °C 100 °C   80 %   1   Insertion (optional latching by PCB stop)
egree of protection (IP code) Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-08   IP20   -40 °C 105 °C (depending on power dissipation)   -40 °C 55 °C   -5 °C 100 °C   80 %   1   Insertion (optional latching by PCB stop)
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egree of protection (IP code) Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB unting Mounting type	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-08   IP20   -40 °C 105 °C (depending on power dissipation)   -40 °C 55 °C   -5 °C 100 °C   80 %   Insertion (optional latching by PCB stop)   1.4 mm 1.8 mm   DIN rail mounting
egree of protection (IP code) Specification mbient conditions Max. IP code to attain Ambient temperature (operation) Ambient temperature (storage/transport) Ambient temperature (assembly) Relative humidity (storage/transport) B data Number of PCB holders Type of PCB mount Thickness of the PCB unting Mounting type Mounting position	IEC 60529:1989-11 + AMD 1:1999-11 + AMD 2:2013-08   IP20   -40 °C 105 °C (depending on power dissipation)   -40 °C 55 °C   -5 °C 100 °C   80 %   Insertion (optional latching by PCB stop)   1.4 mm 1.8 mm   DIN rail mounting

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## Classifications

### ECLASS

	ECLASS-11.0	27182702
	ECLASS-13.0	27190601
E٦	IM	
	ETIM 9.0	EC001031
UNSPSC		
	UNSPSC 21.0	31261500

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## Environmental product compliance

China RoHS	Environmentally friendly use period: unlimited = EFUP-e
	No hazardous substances above threshold values

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Phoenix Contact USA 586 Fulling Mill Road Middletown, PA 17057, United States (+717) 944-1300 info@phoenixcon.com